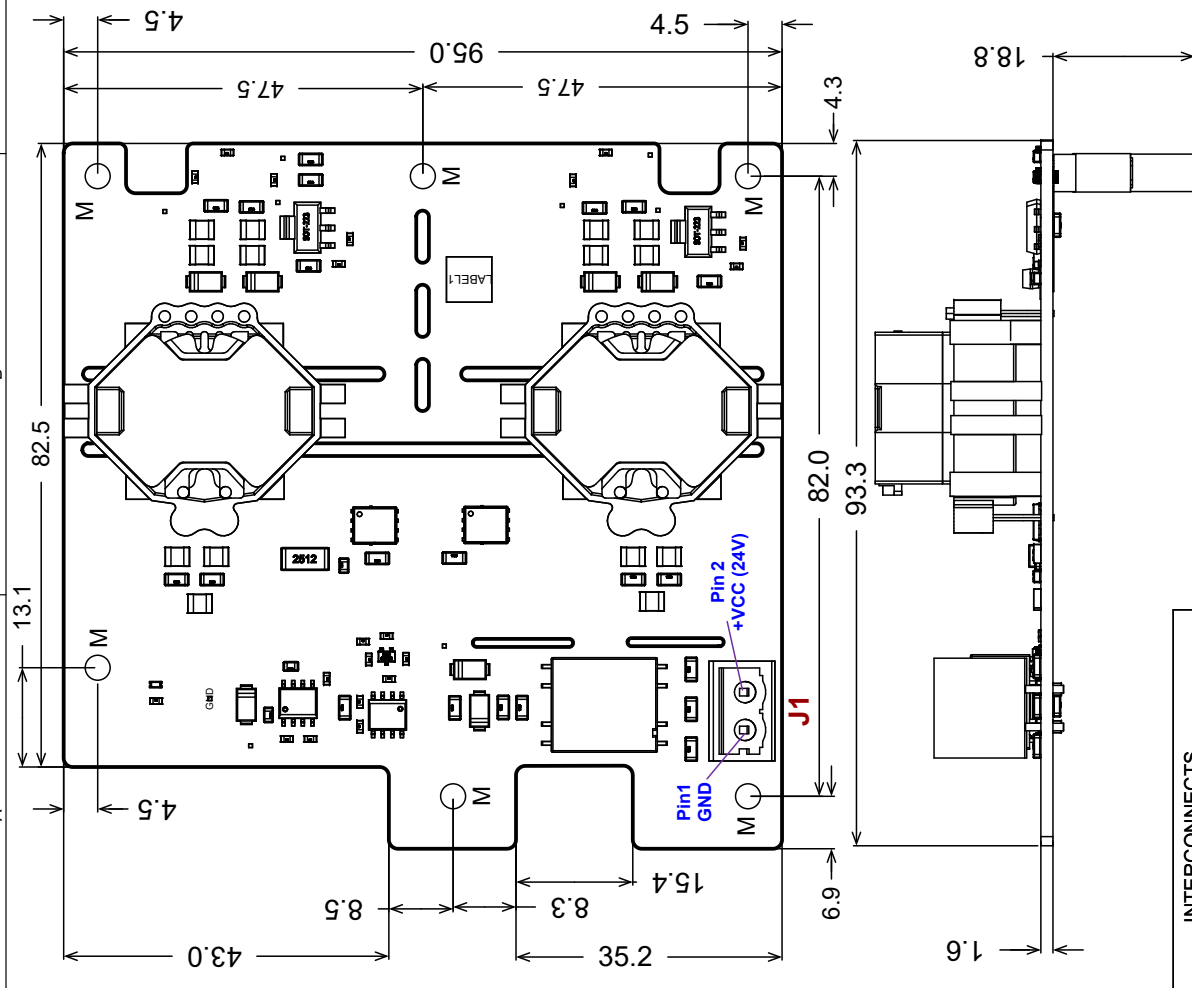


VERSION CONTROL		DESCRIPTION
VER	INITIAL	
1	VG	FINAL RELEASE



INTERCONNECTS	
REF	MFG PART NUMBER
J1	Terminal Block 231-132/001-00
J2, J3	Header ESQ-103-33-L-D

NOTES TOLERANCES UNLESS OTHERWISE SPECIFIED X = ±0.5 XX = ±0.25 XXX = ±0.13 BOARD THICKNESS BOARD OUTLINE 2.28 ± 0.254 X = ±0.1 COMPONENT HOLES AND MOUNTING HOLES Ø03.81 ± 0.076 Ø03.81 ± 0.127 HOLE M = IGBT MOUNTING HOLE HOLE F = FIXING HOLES	
DRWN BY Vipin G	DATE 8/24/2023
APPD BY **	DATE 8/24/2023

MICROCHIP
Microchip Technology Inc.
2025 Washington Avenue
Philadelphia, PA 19146

TITLE XIFM LinPak HV100 Power Supply Board

SIZE	PART NO	VER
A4	XIFM-PS	1

SCALE 1:1 **UNITS** Millimeters **SHEET** 1 of 1